

## LV05 NO CLEAN FLUX CORED WIRE TDS

### FEATURES

- Optimized for Robotic Soldering
- Excellent Wetting Properties
- Excellent Thermal Transfer
- REACH and RoHS Compliant\*
- ROL1 per Current J-STD-004

### DESCRIPTION

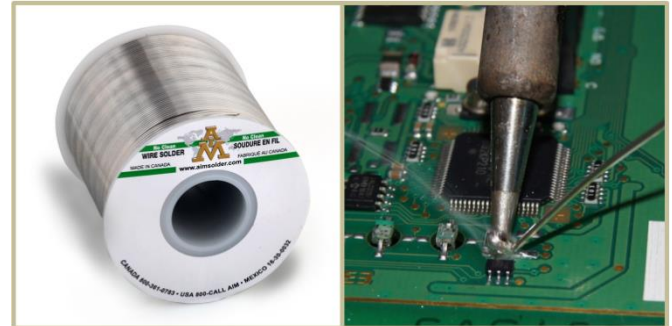
LV05 no clean flux cored wire has been specifically engineered for high volume – high speed electronic assembly. Hand soldering operations benefit from LV05 with fast wetting and low odor resulting in high operator satisfaction. Consistent soldering performance makes LV05 ideal for automated soldering operations. LV05 leaves minimal residues that do not require cleaning and is suitable for automotive and military applications.

### STANDARD AVAILABILITY

LV05 Cored Wire is available in SAC305 alloy in the diameters below. Other diameters may be available upon request.

### APPLICATION

Solder iron tip temperatures are typically between 370° - 425°C (700° - 800°F). Higher or lower temperatures may be used depending on equipment and materials in use.



### HANDLING & STORAGE

TIME	TEMPERATURE
7 Years	< 85°F (< 29°C)

Store cored wire in a clean, dry area away from moisture and sunlight. Do not freeze this product.

### CLEANING

LV05 residues do not require cleaning. However, in applications when cleaning is required, contact AIM for compatibility recommendations.

### SAFETY

Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying Safety Data Sheet for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.

\*All information for reference only. Not to be used as incoming product specifications or for process design. Consult Certificate of Analysis for product specific information.

**DISCLAIMER** The information contained herein is based on data considered accurate and is offered at no charge. Product information is based upon the assumption of proper handling and operating conditions. Liability is expressly disclaimed for any loss or injury arising out of the use of this information or the use of any materials designated. Please refer to <http://www.aimsolder.com/terms-conditions> to review AIM's terms and conditions.

TEST DATA SUMMARY

NAME	TEST METHOD	RESULTS	IMAGE
IPC Flux Classification	J-STD-004	ROLO	
IPC Flux Classification	J-STD-004 Current Rev 3.3.1	ROL1	
NAME	TEST METHOD	RESULTS	IMAGE
Copper Mirror	J-STD-004 Current Rev 3.4.1.1 IPC-TM-650 2.3.32	LOW	
Corrosion	J-STD-004 Current Rev 3.4.1.2 IPC-TM-650 2.6.15	PASS	
Quantitative Halides	J-STD-004 Current Rev 3.4.1.3 IPC-TM-650 2.3.28.1	Br: 0.28% Cl: 0.00%	
Qualitative Halides, Silver Chromate	J-STD-004 Current Rev 3.5.1.1 IPC-TM-650 2.3.33	PASS	
Qualitative Halides, Fluoride Spot	J-STD-004 Current Rev 3.5.1.2 IPC-TM-650 2.3.35.1	No Fluoride	
Surface Insulation Resistance	J-STD-004 Current Rev 3.4.1.4 IPC-TM-650 2.6.3.7	PASS	

\*All information for reference only. Not to be used as incoming product specifications or for process design. Consult Certificate of Analysis for product specific information.

**DISCLAIMER** The information contained herein is based on data considered accurate and is offered at no charge. Product information is based upon the assumption of proper handling and operating conditions. Liability is expressly disclaimed for any loss or injury arising out of the use of this information or the use of any materials designated. Please refer to <http://www.aimsolder.com/terms-conditions> to review AIM's terms and conditions.